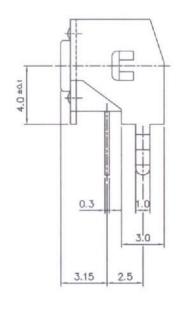
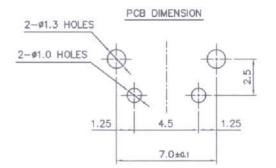


CIRCUIT DIAGRAM







NOTE

1. OPERATING FORCE: 160/250±50gf

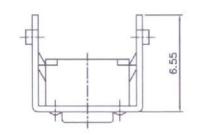
RATING : DC 12V 0.5A
 TRAVEL : 0.25^{+0.2}_{-0.1} m/m

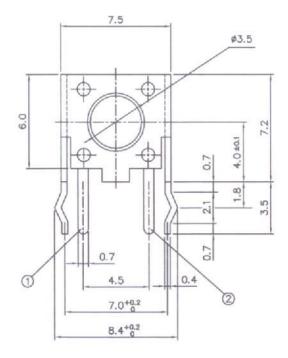
4. CONTACT RESISTANCE : $100m\Omega$ MAX

5. GENERAL TOLERANCE : ±0.3

6. MANUFACTURING SPECIFICATION WOULD BE ACCORDANCE WITH HT0104

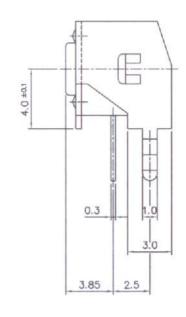
PAR	NO TS	PART NA	ME	Q'TY	MAT	TERIAL	STANDARD	DISPOSITION	REMARKS
A				RIGON- METRY	ÜNIT	SCALE 5 1	TAC	CT SWITCH	HES
A			Al	PPD	СНКВ	DSGD			
A			-/	Xh-	tinh	1/ XP	MODEL		
NO	2.12	CORRECTION							

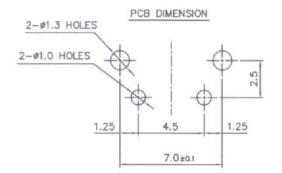




CIRCUIT DIAGRAM







NOTE

1. OPERATING FORCE: 160/250±50gf

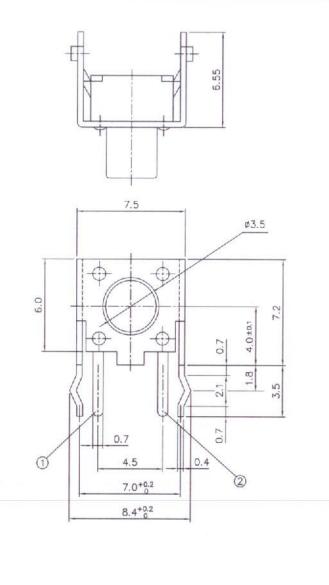
2. RATING: DC 12V 0.5A 3. TRAVEL: 0.25^{+0.2}_{-0.1} m/m

4. CONTACT RESISTANCE : $100m\Omega$ MAX

5. GENERAL TOLERANCE: ±0.3

6. MANUFACTURING SPECIFICATION WOULD BE ACCORDANCE WITH HT0104

PAR	RT NO	PART NAM	E Q	'TY	MAT	TERIAL	STANDARD	DISPOSITION	REMARKS
A A			TRIGO	N-	ÚNIT	SCALE 5 1	TAG	CT SWITCH	HES
A			APPD	/	CHKD	DSGD			
<u>A</u>			- 1CS+	9	Luch	M	MODEL		
NO		CORRECTION				-			



CIRCUIT DIAGRAM

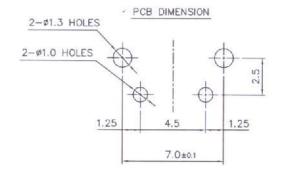


0.3

5.85

3.0

2.5



NOTE

1. OPERATING FORCE: 160, 250±50gf

2. RATING : DC 12V 0.5A

3. TRAVEL : 0.25+0.2 m/m

4. CONTACT RESISTANCE : 100mΩ MAX

5. GENERAL TOLERANCE : ±0.3

6. MANUFACTURING SPECIFICATION WOULD BE ACCORDANCE WITH HT0104

PART NO		PART NAME		Q'TY	MATERIAL		STANDARD	DISPOSITION	REMARKS
<u>A</u>				GON- ETRY	ÛNIT	SCALE 5 1	TAC	CT SWITCH	+
A			AP	PD ,	CHKD	DSGD /			
A				0/	5	history			
A			Ye	1.	Var	1	MODEL		
NO	a 27	CORRECTION							

1. RATINGS

12V DC, 50mA

2. MECHANICAL SPECIFICATIONS

2.1 Actuating Force

As per individual specification

2.2 Return Force

Greater than 50af

2.3 Stop Strenath

Greater than 3kgf (for 3 seconds)

2.4 Travel

0.25 ^{+0.2} mm

2.5 Arrangement of Action

Tactile feed - back

2.6 Operating Temperature Rang

-30°C ~ 80°C. 45 ~ 85%RH

2.7 Storage Temperature Range

-35°C ~ 85°C However, 96 hours maximum for continuous storage

over a range -20°C ~ 30°C and range 70°C ~ 80°C

2.8 Stem withdrawal Force

Greater than 500gf (pull vertically to the opposite direction of

stem operation)

3. ELECTRICAL SPECIFICATIONS

3.1 Contact Arrangement

single pole, single throw

3.2 Contact Resistance

Less than $100 \text{m}\Omega$ when tested by the voltameter method at 5V DC

10mA, or by an ohmmeter allowing a small current at 1000Hz

(measurements to the made with a 100, 130, 160 ± 30 gf, 250 ± 50 gf load

applied vertically at the center of switch)

3.3 Insulation Resistance

Greater than $100M\Omega$ (100V DC insulation resistance meter)

3.4 Dielectric Strength

Capable of withstanding 250V AC, for 1 (one) min.

3.5 Bounce

Less than 10msec (the key shall be struck lightly vertically at its center

at a uniform cycling rate of 3 operations per second)

4. ENDURANCE

4.1 Operating Life

Following 50,000 cycles of operation cycling rate (2 operations per sec.) at a force of depression not exceeding 160 gf with a resistive

load supplying 12V DC, 50mA, the following requirements shall be

satisfied:

4.1.1 Actuating Force

Plus or minus 50% of the initial force

4.1.2 Contact Resistance

Less than 100mΩ

4.1.3 Bounce

Less than 20mΩ

4.2 Moisture Resistance

Following exposure to a 60°C ± 2 °C, 90 \sim 95%RH, environment in a test

chamber for 96 hours and then, out of the chamber, to room condition of normal temperature and humidity for 30 minutes, the requirements

set forth below shall be met.

4.2.1 Insulation Resistance

Greater than $10M\Omega$

4.2.2 Dielectric Strength

Same as Item 3.4

4.2.3 Contact Resistance 4.3 Heat Resistance Same as Item 3.2

Following exposure to an 85°C environment in a test chamber for 96

hours and then, out of the chamber, to room condition of normal temperature and humidity for 30 minutes, the requirements in Items

2 and 3 shall be satisfied.

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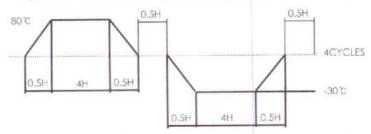
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4.4 Resistance to Low Temperature

Following exposure to a -40°C environment in a test chamber, to room condition of normal temperature and humidity for 30 minutes, the requirements in Items 2 and 3 shall be met.

4.5 Thermal Cycling



Following 5 cycles of a thermal cycling test, on cycle of which is prescribed in the diagram above, the requirements in Items 2 and 3 shall be met.

4.6 Shock Resistance

Following application of an impact shock of 30G in accordance with the method 205, MIL - STD - 202, the requirements in Items 2 and 3 shall be met.

4.7 Vibration Resistance

Following the test conducted according to the method 201,

MIL - STD -202, the switch under test shall conform to the requirements in Items 2 and 3 without any sign of defect both in appearance and

actuation.

5. AUTOMATIC SOLDERING CONDITIONS (in case he automatic flow soldering is to be used)

5.1 Soldering Temperature

230℃ max

5.2 Soldering Time

Continuous dipping duration shall not exceed 5 second.

5.3 Permissible Soldering Times

2 time max

(twice soldering would be dipped after the temperature goes down

to a normal temperature)

5.4 Preheat Temperature

100°C max

(circumferential temperature of the printed writing board)

5.5 Preheat Time

45 seconds max

5.6 Flux Streaming

Flux streaming shall be controlled so that it shall not swell beyond

the printed writing board where components are installed.

5.7 Other Precautions

(1) Flux shall not be applied to switch terminals and the part mounting surface of the P.W. board before soldering.

(2) Do not wash to switch after soldering.

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